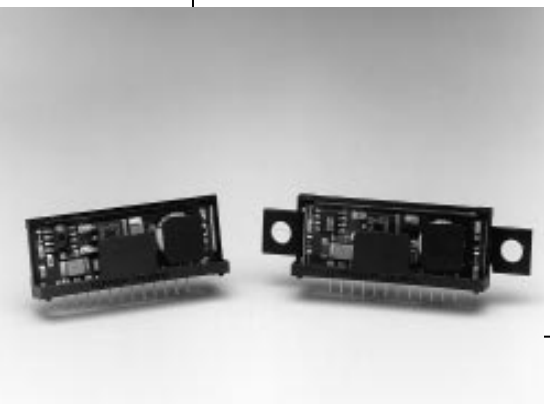
PT6305 Series

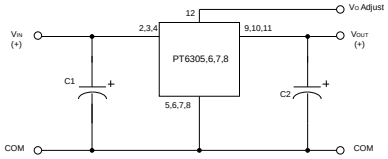
3 AMP HIGH-PERFORMANCE ADJUSTABLE ISR



- Single-Device 5V to 3V Power
- 85% Efficiency
- Small SIP Footprint: 0.36" x 2.00" x 0.60"(H)
- Wide Input Voltage Range: +4.5V to +9.0V
- Internal Short Circuit Protection
- Over-Temperature Protection

The PT6305N is Power Trends' new high performance +5V to +3.3V, 3 Amp, 12-Pin SIP (Single In-line-Package) Integrated Switching Regulator (ISR). This high-performance ISR allows easy integration of low-power 3.3V logic IC's into existing 5V systems without redesigning the central power supply. Only one external capacitor is required for proper operation. The PT6306,7,8 can be used to power high-speed data buses (+2.1V), or the new GTL (+1.2V) logic buses.

Standard Application

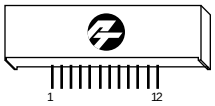


C_1 = Optional electrolytic (100µF)
C_2 = Required 100µF electrolytic (No tantalum)
See capacitor application note on page 43.

Pin-Out Information

Pin No.	Function
1	N/C
2	V_{in}
3	V_{in}
4	V_{in}
5	GND
6	GND

Pin No.	Function
7	GND
8	GND
9	V_{out}
10	V_{out}
11	V_{out}
12	Adjust (See page 40.)



Ordering Information

PT6305☐ = +3.3 Volts
PT6306☐ = +1.8 Volts
PT6307☐ = +2.1 Volts
PT6308☐ = +1.2 Volts
(For dimensions, see page 66.)

PT Series Suffix (PT1234X)

Case/Pin Configuration	Heat Tab Configuration: *None*	*Side*
Vertical Through-Hole	N	R
Horizontal Through-Hole	A	G
Horizontal Surface Mount	C	B

(See Thermal Application Notes on page 44 for heat tab application data.)

Specifications

Characteristics (T_a=25°C unless noted)	Symbols	Conditions		PT6305 SERIES Min	Typ	Max	Units
Output Current	I_o	4.5 ≤ V_{in} ≤ V_{in} MAX		0.3	—	3.0**	ADC
Current Limit	I_{cl}	V_{in} = +5V		—	3.6	5.0	ADC
Short Circuit Current	I_{sc}	V_{in} = +5V		—	5.0	—	Apk
Input Voltage Range	V_{in}	0.3A ≤ I_o ≤ 3.0A	PT6305N	4.5	—	9	VDC
			PT6306N	4.5	—	9	VDC
			PT6307N	4.5	—	9	VDC
			PT6308N	4.5	—	6.0	VDC
Static Voltage Tolerance	V_o	V_{in} = +5V, I_o = 3.0A, 0°C ≤ T_a ≤ +70°C	PT6305N	3.2	3.3	3.4	VDC
			PT6306N	1.7	1.8	1.9	VDC
			PT6307N	2.0	2.1	2.2	VDC
			PT6308N	1.1	1.2	1.3	VDC
Line Regulation	Reg_{line}	4.5V ≤ V_{in} ≤ 5.5V, I_o = 3.0A		—	±25	±50	mV
Load Regulation	Reg_{load}	V_{in} = +5V, 0.3 ≤ I_o ≤ 3.0A		—	±25	±50	mV
V_o Ripple/Noise pk-pk	V_n	V_{in} = 5V, I_o = 3.0A		—	66	—	mV
Transient Response	t_{tr}	I_o step between 1.5A and 3.0A		—	200	—	µSec
with C_2 = 100µF	V_{os}	V_o over/undershoot		—	200	—	mV
Efficiency	η	V_{in} = +5V, I_o = 1.5A	PT6305N	—	85	—	%
			PT6306N	—	74	—	%
			PT6307N	—	77	—	%
			PT6308N	—	63	—	%
		V_{in} = +5V, I_o = 3.0A	PT6305N	—	80	—	%
			PT6306N	—	68	—	%
			PT6307N	—	72	—	%
			PT6308N	—	57	—	%
Switching Frequency	f_o	4.5 ≤ V_{in} ≤ V_{in} MAX, 0.3A ≤ I_o ≤ 3.0A		500	650	800	KHz
Operating Temperature	T_a	Free Air Convection (40-60 LFM) Over V_{in} and I_o Ranges		0	—	+70*	°C
Thermal Resistance	θ_{ja}	Free Air Convection (40-60 LFM)		—	25	—	°C/W
Storage Temperature	T_s	—		-40	—	+125	°C
Mechanical Shock	Per Mil-STD-883D, Method 2002.3 Condition A, 1 msec, Half Sine, mounted to a fixture			—	—	500	G's
Mechanical Vibration	Per Mil-STD-883D, Method 2007.2 Condition A, 20-2000 Hz			—	—	15	G's
Weight	—	—		—	11.2	—	grams
Relative Humidity	—	Non-condensing		0	—	95	%

*See Thermal Derating chart. **The PT6305 Series can be easily paralleled to provide output current in multiples of 3 amps. Please contact a Power Trends' Application Engineer for the appropriate application note. ***Note:*** *The PT6305 Series requires a 100µF electrolytic capacitor for proper operation in all applications.*

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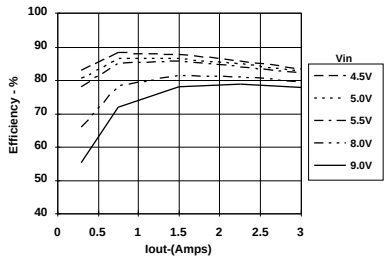
CHARACTERISTIC DATA

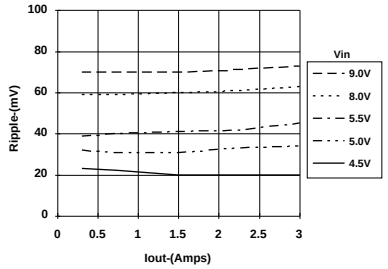
PT6305, 3.3 VDC

(See Note 1)

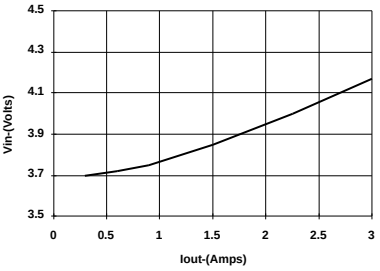
Efficiency vs Output Current



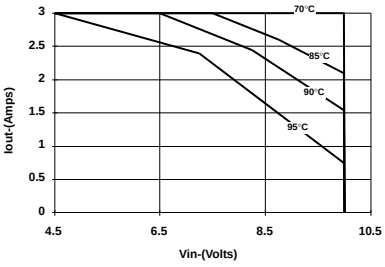
Ripple vs Output Current



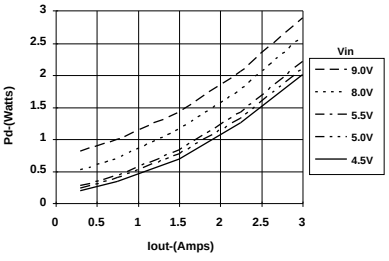
Minimum Input Voltage (See Note 2)



Thermal Derating (T_a) (See Note 3)



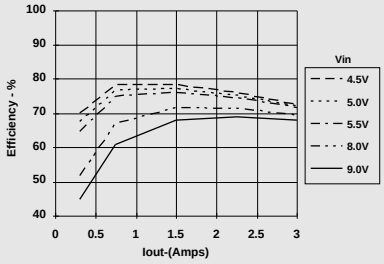
Power Dissipation vs Output Current



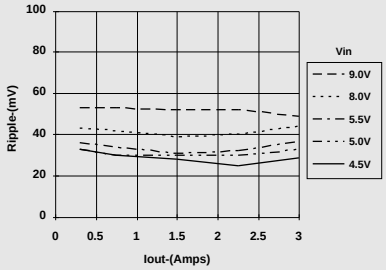
PT6307, 2.1 VDC

(See Note 1)

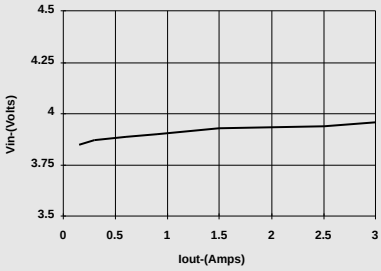
Efficiency vs Output Current



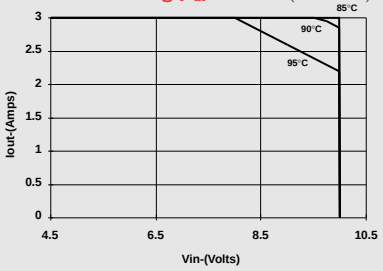
Ripple vs Output Current



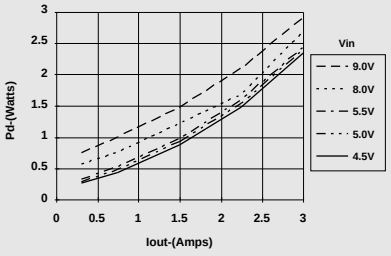
Minimum Input Voltage (See Note 2)



Thermal Derating (T_a) (See Note 3)



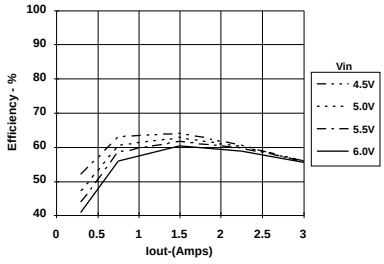
Power Dissipation vs Output Current



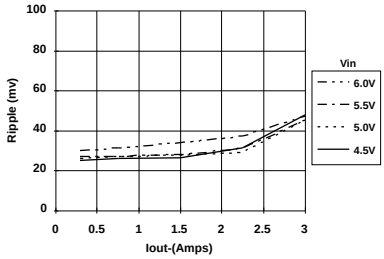
PT6308, 1.2 VDC

(See Note 1)

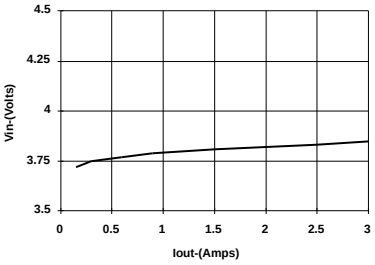
Efficiency vs Output Current



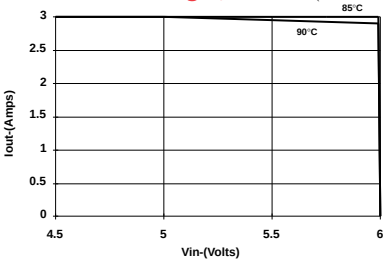
Ripple vs Output Current



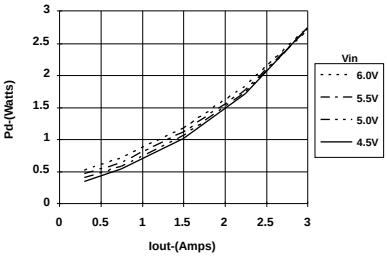
Minimum Input Voltage (See Note 2)



Thermal Derating (T_a) (See Note 3)



Power Dissipation vs Output Current



Note 1: *All data listed in the above graphs, except for derating data, has been developed from actual products tested at 25°C. This data is considered typical data for the ISR.*
Note 2: *Minimum V_{in} data is typical and is not guaranteed. The data corresponds to a 2% output voltage drop.*
Note 3: *Thermal derating graphs are developed in free air convection cooling of 40-60 LFM with no optional heat tab soldered in a printed circuit board. (See Thermal Application Notes).*

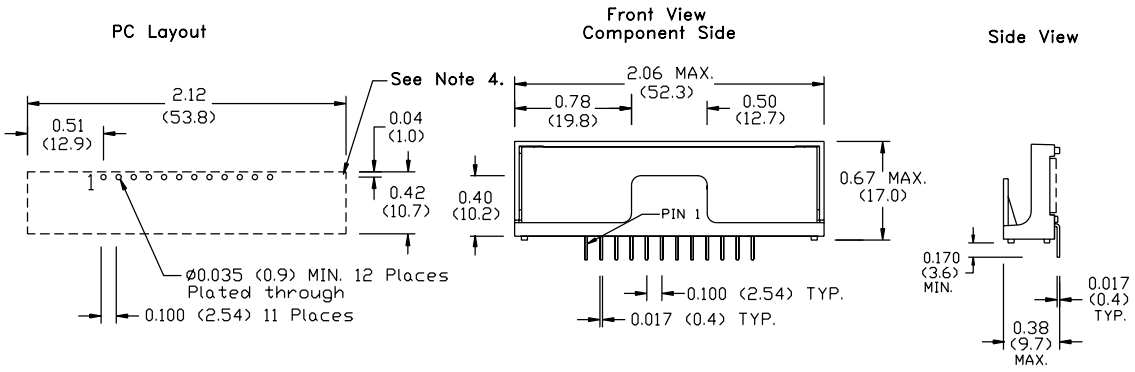
Product families using this package style:
PT6400
PT5060

Package Style 300
Suffix A, C, D, E, N, P

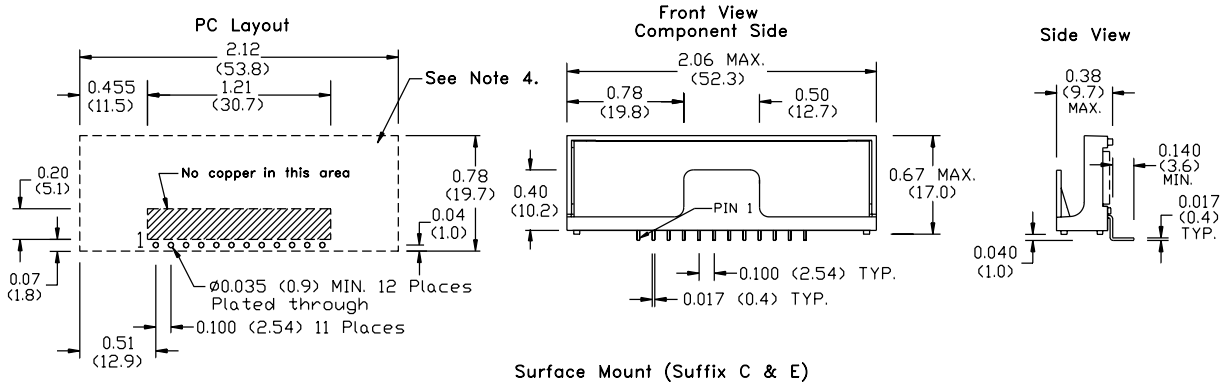
PACKAGE INFORMATION AND DIMENSIONS

Revised 2/11/2000

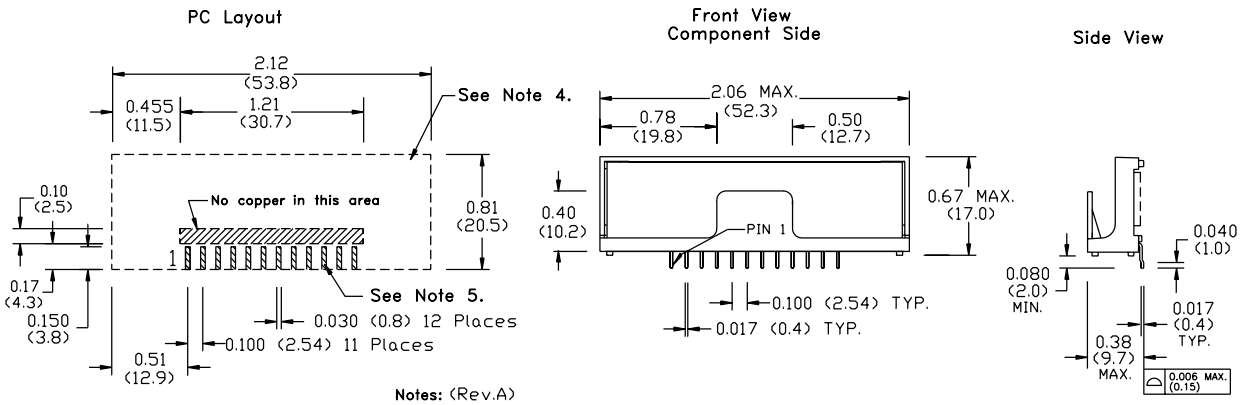
Vertical Through–Hole Mount (Suffix N & P)



Horizontal Through–Hole Mount (Suffix A & D)



Surface Mount (Suffix C & E)



Notes: (Rev.A)
1: All dimensions are in inches (mm).
2: 2 place decimals are ±.030 (±0.8mm).
3: 3 place decimals are ±.010 (±0.3mm).
4: Recommended mechanical keep out area.
5: Power pin connections should utilize two or more vias per input, ground and output pin.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
PT6305B	LIFEBUY	SIP MODULE	ECK	12	12	TBD	Call TI	Level-1-215C-UNLIM	
PT6305C	LIFEBUY	SIP MODULE	ECC	12	12	TBD	Call TI	Level-1-215C-UNLIM	
PT6305N	LIFEBUY	SIP MODULE	ECD	12	12	TBD	Call TI	Level-1-215C-UNLIM	
PT6306A	NRND	SIP MODULE	ECA	12		TBD	Call TI	Call TI	
PT6306B	NRND	SIP MODULE	ECK	12		TBD	Call TI	Call TI	
PT6306C	NRND	SIP MODULE	ECC	12		TBD	Call TI	Call TI	
PT6306G	NRND	SIP MODULE	ECG	12		TBD	Call TI	Call TI	
PT6306R	NRND	SIP MODULE	ECE	12		TBD	Call TI	Call TI	
PT6308A	LIFEBUY	SIP MODULE	ECA	12	12	TBD	Call TI	Level-1-215C-UNLIM	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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